



ABS1 THRU ABS10

MINI SILICON SURFACE MOUNT BRIDGE RECTIFIER

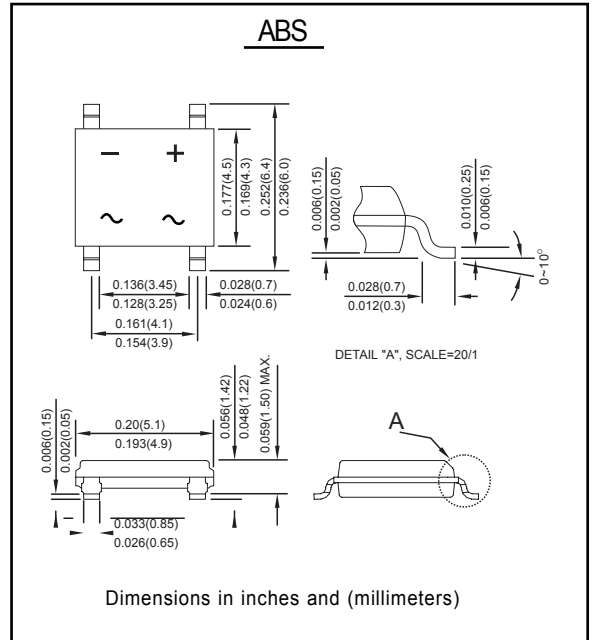
Reverse Voltage - 100 to 1000 Volts Forward Current - 1.0 Ampere

FEATURES

- Ideal for printed circuit board
- Reliable low cost construction technique results in inexpensive product
- High temperature soldering guaranteed :
260°C / 10 seconds / 0.375" (9.5mm)
lead length at 5 lbs., (2.3 kg) tension

MECHANICAL DATA

- Case : Molded Plastic
- Epoxy : Device has UL flammability classification 94V-0
- Mounting Position : Any
- Marking : Type Number



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Characteristic	Symbol	ABS1	ABS2	ABS4	ABS6	ABS8	ABS10	Unit
Peak Repetitive Reverse Voltage	V _{RRM}							
Working Peak Reverse Voltage	V _{RWM}	100	200	400	600	800	1000	V
DC Blocking Voltage	V _R							
RMS Reverse Voltage	V _{R(RMS)}	70	140	280	420	560	700	V
Average Rectified Output Current	I _O				0.8			A
-On glass-epoxy P.C.B.					1.0			
-On aluminum substrate								
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}				30			A
I ² t Rating for Fusing (t < 8.3ms)	I ² t				10			A ² s
Forward Voltage per element @I _F = 0.4A	V _{FM}				0.95			V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C	I _{RM}				10			μA
					150			
Typical Thermal resistance Junction to Lead					25			
On aluminum substrate	R _{θJA}				62.5			°C/W
On Glass-Epoxy substrate	R _{θJL}				25			
Operating and Storage Temperature Range	T _J , T _{STG}				-55 to +150			°C

Note: 1. On aluminum substrate P.C.B. with an area of 0.8×0.8"(20×20mm) mounted on 0.05×0.05"(1.3×1.3mm) solder pad.
2. On glass epoxy P.C.B. mounted on 0.05×0.05"(1.3×1.3mm) pads.



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RATINGS AND CHARACTERISTIC CURVES

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

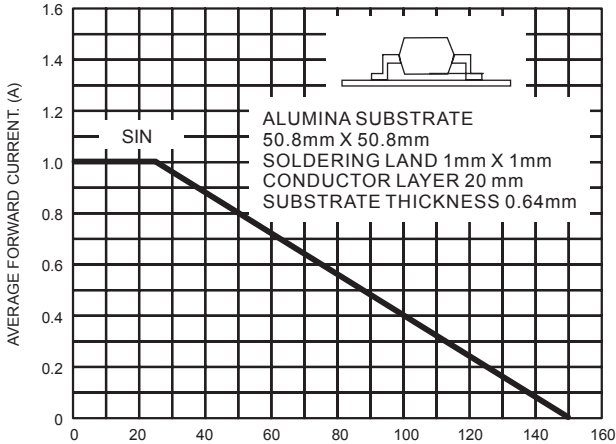


FIG.2- TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT

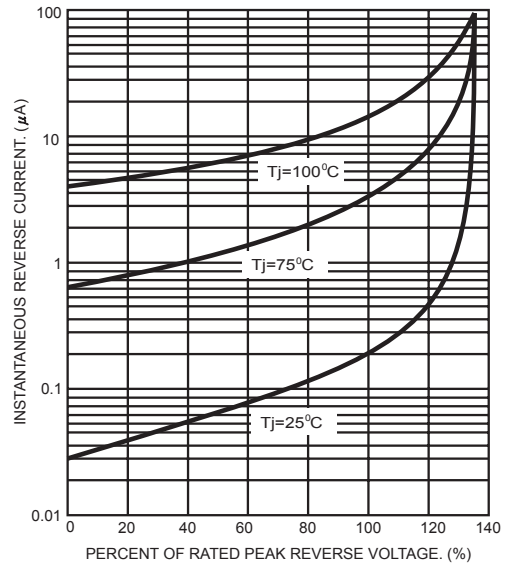


FIG.3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

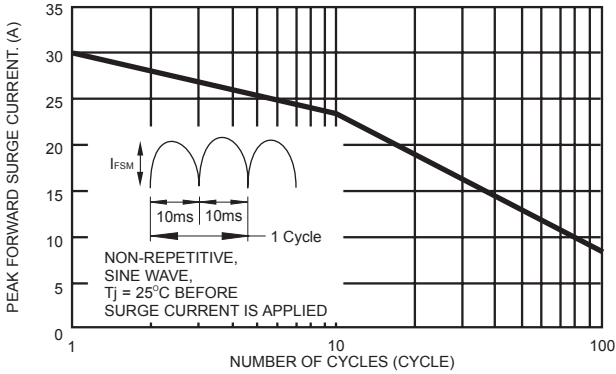


FIG.4- TYPICAL JUNCTION CAPACITANCE

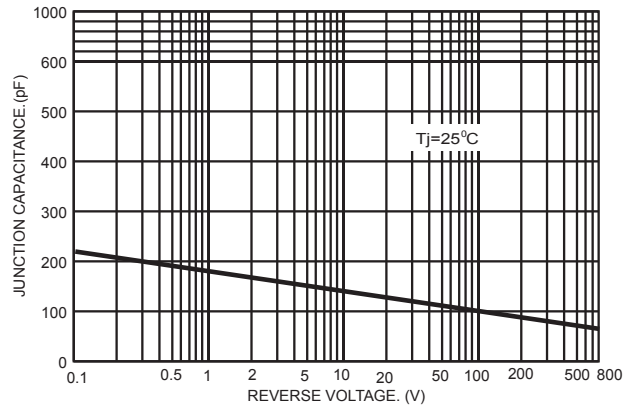


FIG.5- TYPICAL FORWARD CHARACTERISTICS

